

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	24	lee-won-jun.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/09 10:26
S2	5	lee-won-jun.in.	EPO; JPO; DERWENT	OR	ON	2006/01/04 11:41
S3	6290	((438/253) or (438/254) or (438/255) or (438/396) or (438/397) or (437/398)).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2006/01/09 12:56
S4	797	((438/254) or (438/397)).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2006/01/09 10:28
S5	4	S4 and bubble	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/09 10:29
S6	793	S4 and (etch\$4 recess\$4 protru\$5 remov\$4 reduc\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/09 12:14
S7	558	S4 and (etch\$4 recess\$4 protru\$5 remov\$4 reduc\$4).ab.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/09 10:30
S8	720	S4 and (etch\$4 recess\$4 protru\$5 remov\$4 reduc\$4).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/09 10:30
S9	538	S7 and S8	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/09 10:30
S10	339	S9 and (wet aqueous liquid) near2 etch\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/09 12:15
S11	43	S9 and (wet aqueous liquid) near2 etch\$4.ab.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/09 10:30
S12	133	S9 and (wet aqueous liquid) near2 etch\$4.clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/09 10:30

S13	147	S11 S12	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/09 11:41
S14	293	S3 and (protruding protrusion)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/09 11:41
S15	128	S3 and (protruding protrusion) same etch\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/09 11:41
S16	117	S15 not S13	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/09 11:41
S17	36431	(protrusion protrud\$4) same (etch\$4 recess\$4 protru\$5 remov\$4 reduc\$4) same electrode	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/09 12:15
S18	209	S17 same (wet aqueous liquid) near2 etch\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/09 12:15
S19	2	S18 same bubble	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/09 12:16
S20	197	S18 not (S19 S13 S16)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/09 12:16
S21	6290	((438/253) or (438/254) or (438/255) or (438/396) or (438/397) or (437/398)).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2006/01/09 12:56
S22	174	S21 and (remov\$4 near1 photoresist with (chemical solution wet))	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/09 13:10
S23	154	S22 and @ad<"20020922"	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/09 12:57
S24	247	S21 and (remov\$4 near1 photoresist with (etch\$4))	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/09 13:10

S25	72	S22 and S24	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/09 13:10
S26	56	S23 and S25	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/09 13:10